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Recent Advances in 2D Materials for Smart Electronics

Guest Editor:

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Message from the Guest Editor

Dear Colleagues,

2D materials not only perform metal-like superior physicochemical properties but also exhibit advantages such as good processability, low density, high flexibility as soft materials do. This uniqueness enables the promising application of 2D materials in electronic systems to embed enhanced functionalities along with significantly improved mechanical flexibilities, which are demanded by traditional "hard" electronics with restricted application scenarios.

However, with the introduction of 2D materials into traditional material systems, various candidates and fabrication approaches have been involved. Meanwhile, the data processing and analysis of certain electronic systems (e.g., full body tracking, biosensing, health monitoring) are also quite resource exhaustive.

The current Special Issue focuses on (1) next-generation 2D materials integrated smart electronics with diverse functionalities and applications; (2) efficient approaches to accelerate the materials exploration/fabrication and data processing for 2D materials integrated electronics with the help of artificial intelligence and big data.

Dr. Lin Jing *Guest Editor*













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Message from the Editor-in-Chief

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